Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A network comprising:

a first conductor plane and a second conductor plane;

a substrate; and

a ceramic intermediate layer that separates the first conductor plane and the second conductor plane, the ceramic intermediate layer comprising an interlayer contact;

a transformation line formed in or on the substrate and having a predetermined electrical length, the transformation line comprising;

a first part having a bent-over configuration, the first part being disposed in the first conductor plane; and

a second part having a bent-over configuration, the second part being disposed in the second conductor plane, the second part being electrically connected to the first part by the interlayer contact;

wherein the first and second parts of the transformation line comprise conductor segments that are straight and that are joined at right angles; [[and]]

wherein at least some of the conductor segments comprise parallel conductor segments disposed in the first and the second conductor planes, the parallel conductor segments at least partially overlapping and being capacitively coupled such that a resulting capacitive coupling is adjustable by adjusting overlap areas of the parallel conductor segments; and

wherein widths of conductor segments in at least one of the first and second conductor planes are different and the widths are configured to compensate for cross-couplings between different segments, and to generate an impedance matching to an environment greater than about 25 dB.

2. (Currently Amended) The network of claim [[1]] 6, wherein widths of conductor segments in at least one of the first and second conductor planes are different and the widths are configured to compensate for cross-couplings between different segments, and to generate an impedance matching to an environment greater than about 25 dB.

3. (Previously Presented) The network of claim 16, wherein the width of different ones of the parallel conductor segments is different.

4. (Previously Presented) The network of claim 1, further comprising:

a first shielding plate connected to ground; and

a second shielding plate connected to ground, the second shielding plate being about parallel to the first shielding plate, wherein at least one of the first and second conductor planes is between the first and second shielding plates and is separated from at least one of the first shielding plate and the second shielding plate by at least one ceramic layer.

5. (Previously Presented) The network of claim 1, wherein at least one longitudinal edge of at least one parallel conductor segment disposed in the first conductor plane adjoins at least one longitudinal edge of at least one parallel conductor segment in the second conductor plane, the at least one conductor segment in the first conductor plane being about parallel to the at least one conductor segment in the second conductor plane.

6. (Currently Amended) ~~The network of claim 1,~~ A network comprising:

a first conductor plane and a second conductor plane;

a substrate; and

a ceramic intermediate layer that separates the first conductor plane and the second conductor plane, the ceramic intermediate layer comprising an interlayer contact;

a transformation line formed in or on the substrate and having a predetermined electrical length, the transformation line comprising:

a first part having a bent-over configuration, the first part being disposed in the first conductor plane; and

a second part having a bent-over configuration, the second part being disposed in the second conductor plane, the second part being electrically connected to the first part by the interlayer contact;

wherein the first and second parts of the transformation line comprise conductor segments that are straight and that are joined at right angles;

wherein at least some of the conductor segments comprise parallel conductor segments disposed in the first and the second conductor planes, the parallel conductor segments at least partially overlapping and being capacitively coupled such that a resulting capacitive coupling is adjustable by adjusting overlap areas of the parallel conductor segments; and

wherein all of the conductor segments have a width greater than or equal to a length of a conductor segment having a shortest length.

7. (Currently Amended) The network of claim [[4]]1, wherein the transformation line comprises a "tri-plate" line and includes first and second shielding plates, wherein the first and second shielding plates are connected to ground.

8. (Previously Presented) The network of claim 1, wherein the transformation line is a lambda/4 line.

9. (Previously Presented) The network of claim 1, wherein the transformation line has 50 Ohm impedance matching.

10. (Previously Presented) The network of claim 1, further comprising an element configured to provide impedance matching to a desired value.

11. (Previously Presented) The network of claim 1, wherein the substrate is a multilayer ceramic structure.

12. (Previously Presented) The network of claim 18, wherein the component or module comprises at least one component configured to operate with acoustic waves.

13. (Previously Presented) The network of claim 1, wherein the bent-over configuration of the first part and the second part of the transmission line is a Greek fret pattern.

14. (Previously Presented) The network of claim 1, wherein the interlayer contact comprises through-plating.

15. (Previously Presented) The network of claim 1, wherein the parallel conductor segments are configured such to generate the predetermined electrical length and predetermined impedance of the transformation line.

16. (Currently Amended) ~~The network of claim 1,~~ A network comprising:

a first conductor plane and a second conductor plane;

a substrate; and a ceramic intermediate layer that separates the first conductor plane and the second conductor plane, the ceramic intermediate layer comprising an interlayer contact;

a transformation line formed in or on the substrate and having a predetermined electrical length, the transformation line comprising;

a first part having a bent-over configuration, the first part being disposed in the first conductor plane; and

a second part having a bent-over configuration, the second part being disposed in the second conductor plane, the second part being electrically connected to the first part by the interlayer contact;

wherein the first and second parts of the transformation line comprise conductor segments that are straight and that are joined at right angles;

wherein at least some of the conductor segments comprise parallel conductor segments disposed in the first and the second conductor planes, the parallel conductor segments at least partially overlapping and being capacitively coupled such that a resulting capacitive coupling is adjustable by adjusting overlap areas of the parallel conductor segments; and

wherein widths of parallel conductor segments in one of the first and second conductor planes and of respective parallel conductor segment in the other of the first and second conductor planes are different and the widths are configured to compensate for cross-couplings between different segments and to generate an impedance matching to an environment to the extent of greater than 25 dB.

17. (Currently Amended) ~~The network of claim 7,~~ A network comprising:

a first conductor plane and a second conductor plane;

a substrate;

a ceramic intermediate layer that separates the first conductor plane and the second conductor plane, the ceramic intermediate layer comprising an interlayer contact;

a transformation line formed in or on the substrate and having a predetermined electrical length, the transformation line comprising;

a first part having a bent-over configuration, the first part being disposed in the first conductor plane; and

a second part having a bent-over configuration, the second part being disposed in the second conductor plane, the second part being electrically connected to the first part by the interlayer contact;

a first shielding plate connected to ground; and

a second shielding plate connected to ground, the second shielding plate being about parallel to the first shielding plate, wherein at least one of the first and second conductor planes is between the first and second shielding plates and is separated from at least one of the first shielding plate and the second shielding plate by at least one ceramic layer;

wherein the first and second parts of the transformation line comprise conductor segments that are straight and that are joined at right angles;

wherein at least some of the conductor segments comprise parallel conductor segments disposed in the first and the second conductor planes, the parallel conductor segments at least partially overlapping and being capacitively coupled such that a resulting capacitive coupling is adjustable by adjusting overlap areas of the parallel conductor segments;

wherein the transformation line comprises a "tri-plate" line and includes the first and second shielding plates; and

wherein a thickness of the ceramic layers is about the same as a thickness of the shielding plates.

18. (Previously Presented) The network of claim 11, wherein the multilayer ceramic structure is configured to provide support for a component or a module.